



ThermAvant Technologies LLC

Columbia, Missouri

TOPIC NUMBER: AF112-057

TOPIC TITLE:

Next-Generation Microchip Carrier for Cooling of Satellite Payload Electronics

TECHNICAL PROJECT OFFICE:

AFRL Space Vehicles Directorate
Kirtland AFB, NM



- Addresses key microchip thermal issues in space vehicles
- Based on emerging, mostly untapped technology
- Led to commercial sales and job growth for the company

SOLUTION TO MICROCHIP OVERHEATING IN SPACE APPLICATIONS DRIVES COMMERCIAL SUCCESS

A new microchip cooling technology that paves the way for higher-performance electronics on spacecraft is spurring growth at a Missouri-based small business.

With support from the Air Force Small Business Innovation Research/Small Business Technology Transfer Program, ThermAvant Technologies successfully demonstrated advanced thermal management solutions for spacecraft electronics based on an emerging, but mostly untapped technology. Since its initial research project for the Air Force, the company has entered dozens of agreements to supply the solution for aerospace and defense applications.

